

# LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1764ET-2.5#PBF

(Engineering Calculation)

TO-220

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TOTAL MASS (g):

1.991727

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.005437	1000000	2729.792		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	1.428754	998500	717344.2		
		Iron (Fe)	7439-89-6	0	0	0		
		Phosphorus (P)	7723-14-0	0	0	0		
		Zinc (Zn)	7440-66-6	0	0	0		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0.002146	1500	1077.457		
		<b>Lead Frame Total:</b>				<b>1.433046</b>	<b>1000000</b>	<b>719499.1</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.01139827	1000000	5722.805		
		<b>External Plating Total:</b>				<b>0.01139827</b>	<b>1000000</b>	<b>5722.805</b>
		Inter. Plating Ni	7440-02-0	0.01	834028.4	5020.768		
		Inter. Plating Ag	7440-22-4	0.00199	165971.6	999.1328		
		<b>Internal Plating Total:</b>				<b>0.01199</b>	<b>1000000</b>	<b>6019.9</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0	0	0		
		Tin (Sn)	7440-31-5	0.000121	50000	60.75129		
		Lead (Pb)	7439-92-1	0.002297	950000	1153.27		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Resin (EP)		0	0	0		
<b>Die Attach Total:</b>				<b>0.002418</b>	<b>1000000</b>	<b>1214.022</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.05427	103000	27247.71		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.471567	895000	236762.8		
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0		
		Metal Hydroxid		0	0	0		
		Carbon Black (C)	1333-86-4	0.001054	2000	529.1889		
		<b>Encapsulation Total:</b>				<b>0.526891</b>	<b>1000000</b>	<b>264539.7</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000547	1000000	274.636		